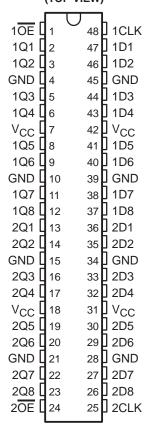
SCBS205C - MARCH 1993 - REVISED MAY 1997

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   < 0.8 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

### description

The 'ABT16374A are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

SN54ABT16374A . . . WD PACKAGE SN74ABT16374A . . . DGG OR DL PACKAGE (TOP VIEW)



These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16374A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16374A is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

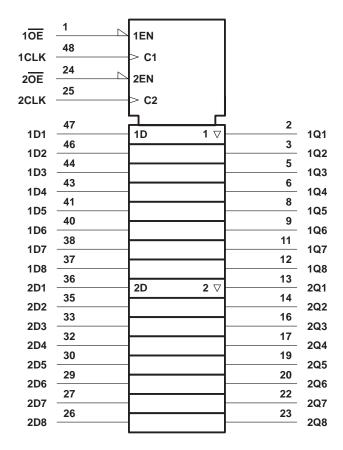


SCBS205C - MARCH 1993 - REVISED MAY 1997

#### **FUNCTION TABLE** (each flip-flop)

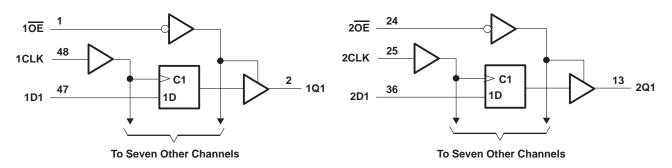
	INPUTS		OUTPUT
ŌĒ	CLK	D	Q
L	1	Н	Н
L	$\uparrow$	L	L
L	H or L	Χ	Q <sub>0</sub>
Н	X	Χ	Z

# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





SCBS205C - MARCH 1993 - REVISED MAY 1997

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, I <sub>O</sub> : SN54ABT16374A	96 mA
SN74ABT16374A	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			SN54ABT	16374A	SN74ABT	16374A	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V	
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	Vcc	0	Vcc	V	
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SCBS205C - MARCH 1993 - REVISED MAY 1997

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	RAMETER	TEST O	ONDITIONS	7	T <sub>A</sub> = 25°C	;	SN54ABT	16374A	SN74ABT1	16374A	UNIT
PAR	KAMETER	l lesi c	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ <sub>\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\</sub>		V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Vai		V00 - 45 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 64 \text{ mA}$				0.55*				0.55	V
V <sub>hys</sub>					100						mV
IĮ		$V_{CC} = 0 \text{ to } 5.5 \text{ V}$	$V_1 = V_{CC}$ or GND			±1		±1		±1	μΑ
l <sub>OZPU</sub> ‡	‡	$V_{CC} = 0 \text{ to } 2.1 \text{ V}_{O} = 0.5 \text{ to } 2.7 \text{ V}_{O}$	V, V, <del>OE</del> = X			±50		±50		±50	μΑ
l <sub>OZPD</sub> ‡	‡	$V_{CC} = 2.1 \text{ V to } V_{O} = 0.5 \text{ to } 2.7$			±50		±50		±50	μА	
lozh		V <sub>CC</sub> = 2.1 V to V <sub>O</sub> = 2.7 V, OE			10		10		10	μА	
lozL		V <sub>CC</sub> = 2.1 V to V <sub>O</sub> = 0.5 V, OE				-10		-10		-10	μА
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX	Outputs high	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 5.5 V			50		50		50	μΑ
IO§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
	Outputs high					2		2		2	
loo	Outputs low	V <sub>CC</sub> = 5.5 V, I <sub>O</sub>				72		72		72	mA
Icc	Outputs VI = VCC or GN disabled		D			2		2		2	IIIA
ΔICC¶		V <sub>CC</sub> = 5.5 V, Or Other inputs at V			1.5		1.5		1.5	mA	
Ci		V <sub>I</sub> = 2.5 V or 0.5	5 V		3.5						pF
Co		$V_0 = 2.5 \text{ V or } 0.$	5 V		9.5						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

### timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C <sup>#</sup>		SN54ABT1	16374A	SN74ABT	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before CLK↑	1.1		1.3		1.1		ns
th	Hold time, data after CLK↑	1.3		1.5		1.3		ns

<sup>#</sup>These values apply only to the SN74ABT16374A.



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> This parameter is characterized, but not production tested.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

SCBS205C - MARCH 1993 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

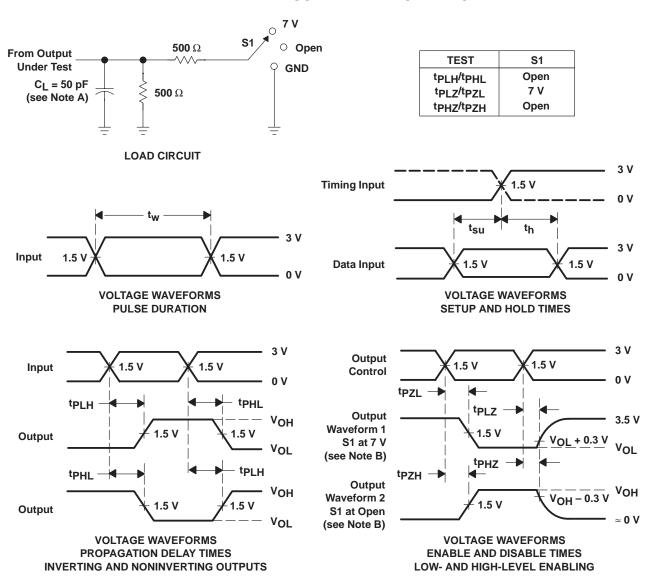
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			150			150		MHz
<sup>t</sup> PLH	CLK	Q	1.8	4.3	5.7	1.5	6.9	ns
<sup>t</sup> PHL	OLK	Q	2.7	4.7	6.1	2.2	6.9	110
<sup>t</sup> PZH	ŌĒ	Q	1.2	3.4	4.8	0.8	6.1	ns
t <sub>PZL</sub>	OE .	Q	1.6	3.5	4.9	1.2	5.5	115
<sup>t</sup> PHZ	ŌĒ	Q	2.2	5.5	8.6	1.8	9.6	nc
t <sub>PLZ</sub>	OL	Q	2.2	4.3	6.2	1.8	7.2	ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			150			150		MHz
t <sub>PLH</sub>	CLK	Q	1.8	4.3	5.4	1.8	6.2	ns
tPHL	OLK	Q	2.7	4.7	5.6	2.7	5.9	113
<sup>t</sup> PZH	ŌĒ	Q	1.2	3.4	4.8	1.2	5.6	ns
tPZL	OE	ų ,	1.6	3.5	4.7	1.6	5.3	115
t <sub>PHZ</sub>	ŌĒ	Q	2.2	5.5	7.1	2.2	8.2	ns
tPLZ			2.2	4.3	5.8	2.2	6.6	115

SCBS205C - MARCH 1993 - REVISED MAY 1997

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 25-Nov-2021

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9320101MXA	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9320101MX A SNJ54ABT16374A WD	Samples
SN74ABT16374ADGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A	Samples
SN74ABT16374ADL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A	Samples
SN74ABT16374ADLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A	Samples
SN74ABT16374ADLRG4	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A	Samples
SNJ54ABT16374AWD	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9320101MX A SNJ54ABT16374A WD	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

## PACKAGE OPTION ADDENDUM

www.ti.com 25-Nov-2021

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54ABT16374A, SN74ABT16374A:

Catalog: SN74ABT16374A

Military: SN54ABT16374A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

www.ti.com 11-Mar-2017

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT16374ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 11-Mar-2017



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABT16374ADLR	SSOP	DL	48	1000	367.0	367.0	55.0



SMALL OUTLINE PACKAGE



### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

### WD (R-GDFP-F\*\*)

#### **CERAMIC DUAL FLATPACK**

### **48 LEADS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2021, Texas Instruments Incorporated